

Editorial plan

No. 1 January/February 2017

Embedded and high-speed systems, micro and nanoelectronics

on sale: 6. 1. 2017

Embedded systems, PCB with embedded components, high-speed circuitry, components, design and development, PCB design, application software, manufacturing, measuring and testing, news, applications, trends

No. 2 March/April 2017

Exhibition AMPER, embedded world, WIN EURASIA Automation, LOPE-C Industrial – special – power – organic – printed and wearable electronics

on sale: 7. 3. 2017

Industrial computers, control systems, power units, used components, circuitry, design and development, application software, PCB design, measuring and testing, manufacturing, technology, materials, news, applications, trends

No. 3 May/June 2017

Exhibition SMT Hybrid Packaging, ELOSYS

Measuring – testing – simulation during design and development, manufacturing and service, reliability

on sale: 5. 5. 2017

Measuring and testing instruments, sensors, methodology, tips and techniques, used components, application software, EMC, signal and power integrity, thermal and reliability analysis, PCB design, design and development, manufacturing, news, applications, trends

No. 4 July/August 2017

Electronics manufacturing

on sale: 7. 7. 2017

PCB fabrication, PCB assembly, soldering, cleaning, inspection, testing, measuring, assembly, product and parts identification, used technologies, for example laser, materials, PCB rework, world-wide manufacturing overview, PCB design, 3D print, CAM software

No. 5 September/October 2017

Exhibition MSV

Wireless – RF – microwave and RFID electronics

on sale: 7. 9. 2017

Components, circuitry, design and development, PCB design, application software, measuring and testing, manufacturing, news, applications, trends

No. 6 November/December 2017

Exhibition productronica

Electronics components

on sale: 7. 11. 2017

Analog, digital, active, passiv, SMT, ASIC, FPGA, false components, special components, interesting circuitry, measuring and testing, design and development, manufacturing, materials, used technology, PCB design, application, software, news, applications, trends

There are the following regular columns in every issue: Design and Development, CAD/CAE/CAM software, Measuring, Fabrication and Manufacturing, Electronic components, Miscellaneous – trends, news, markets development, overviews.

Distribution of printed magazine at exhibitions in 2017:

No.1 – January/February: AMPER

No.2 – March/April: AMPER, embedded world, LOPE-C, WIN EURASIA Automation

No.3 – March/April: SMT Hybrid Packaging, ELOSYS

No.4 – July/August: MSV

No.5 – September/October: MSV

No.6 – November/December: productronica